



650V FIELD STOP IGBT IN ITO220AB

Description

The DGTD65T15H2TF is produced using advanced Field Stop Trench IGBT Technology, which provides high-performance, excellent quality, and high ruggedness.

Features

- High Ruggedness for Motor Control
- V_{CE(sat)} Positive Temperature Coefficient
- Very Soft, Fast Recovery Anti-Parallel Diode
- Low EMI
- Maximum Junction Temperature +175°C
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Applications

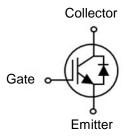
Motor Drive

Mechanical Data

- Case: ITO220AB (Type MC)
- Case Material: Molded Plastic. "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Terminals: Finish—Matte Tin Plated Leads.
 Solderable per MIL-STD-202, Method 208 (23)
- Weight: 1.9 grams (Approximate)



ITO220AB (Type MC)



Device Symbol

Ordering Information (Note 4)

Product	Marking	Quantity		
DGTD65T15H2TF	DGTD65T15H2	1000 per Box in Tubes (Note 5)		

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3).compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.
- 5. 50 devices per tube.

Marking Information



);; = Manufacturer's Marking
DGTD65T15H2 = Product Type Marking Code
YY = Year (ex: 18 = 2018)
LLLLL = Lot Code
WW = Week (01 to 53)



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic Collector-Emitter Voltage		Symbol	Value	Unit
		V _{CE}	650	V
DC Collector Current Limited by T	$T_C = +25$ °C		30	Α
DC Collector Current, Limited by T _{jmax}	$T_C = +100^{\circ}C$	IC	15	Α
Pulsed Collector Current, tp Limited by Tjmax		I _{Cpuls}	60	Α
Diada Famuand Comment Limited by T	T _C = +25°C	I _F	30	Α
Diode Forward Current Limited by T _{jmax}	$T_C = +100^{\circ}C$		15	Α
Diode Pulsed Current, tp Limited by Tjmax		I _{Fpuls}	60	Α
Gate-Emitter Voltage		V_{GE}	±20	V
Short Circuit Withstand Time $V_{CC} \le 360V$, $V_{GE} = 15V$, $T_i = +150$ °C		t _{SC}	5	μs

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

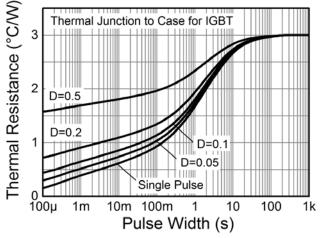
Characteristic	Symbol	Value	Unit	
Power Dissipation Linear Derating Factor (Note 7) T _C = +25°C	P _D	48	W	
T _C = +100°C		24		
Thermal Resistance, Junction to Ambient (Note 6)	R _{OJA}	62	°C/W	
Thermal Resistance, Junction to Case for IBGT (Note 7)	R _{OJC}	3.0		
Thermal Resistance, Junction to Case for Diode (Note 7)	R _{OJC}	5.0		
Operating Temperature	T _i	-40 to +175	°C	
Storage Temperature Range	T _{STG}	-55 to +150		

Note:

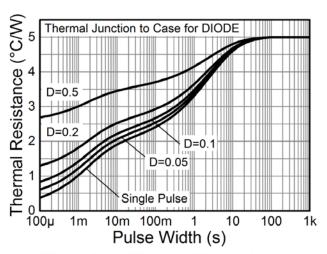
^{6.} For a device mounted in a socket in still air conditions. Collector lead length 10mm. 7. For a device mounted on a Force Cooled Aluminium Heatsink 80x80x60mm.



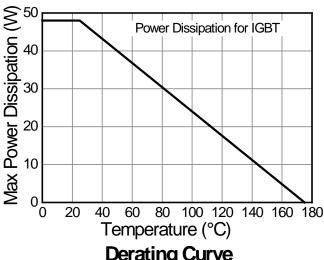
Thermal Characteristics and Derating Information



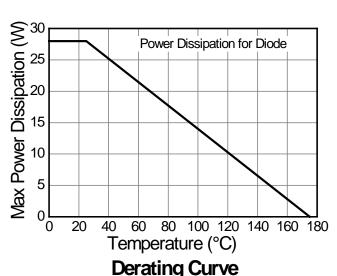
Transient Thermal Impedance



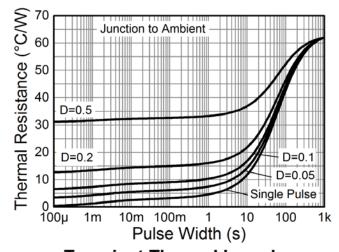
Transient Thermal Impedance



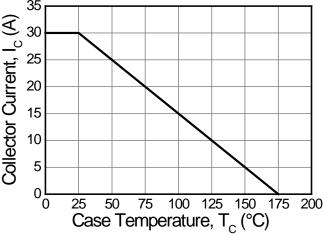
Derating Curve



35



Transient Thermal Impedance



Case Temperature-Collector Current



Electrical Characteristics (@Tj = +25°C, unless otherwise specified.)

Parameter		Symbol	Min	Тур	Max	Unit	Condition	
STATIC CHARACTERISTICS								
Collector-Emitter Breakdown Voltage		BV _{CES}	650			V	$I_C = 2mA$, $V_{GE} = 0V$	
Collector Emitter Seturation Valtage	$T_j = +25^{\circ}C$	\/	_	1.65	2.00	V	I _C = 15A, V _{GE} = 15V	
Collector-Emitter Saturation Voltage	$T_j = +175^{\circ}C$	$V_{CE(sat)}$	_	1.90	_			
Diada Farward Valtage	$T_j = +25^{\circ}C$	\/	_	1.85	2.30	V	V _{GE} = 0V, I _F = 15A	
Diode Forward Voltage	T _j = +175°C	V_{F}	_	1.95	_	V		
Gate-Emitter Threshold Voltage		$V_{GE(th)}$	4.5	5.5	6.5	V	$V_{CE} = V_{GE}$, $I_C = 0.5mA$	
		laa		_	20	μA	$V_{CE} = 650V, V_{GE} = 0V,$	
Zero Gate Voltage Collector Current		Ices			20	μΛ	$T_j = +25$ °C	
Gate-Emitter Leakage Current		I _{GES}	_	_	±100	nA	$V_{GE} = 20V, V_{CE} = 0V$	
DYNAMIC CHARACTERISTICS						1		
Total Gate Charge		Q_g	_	61	_		V _{CF} = 520V, I _C = 15A,	
Gate-Emitter Charge		Q_ge	_	11	_	nC	$V_{GE} = 320V, 10 = 13A,$ $V_{GE} = 15V$	
Gate-Collector Charge		Q_{gc}	_	35	_		VGE = 13V	
Input Capacitance		C _{ies}	_	1129	_		V _{CE} = 25V, V _{GE} = 0V, f = 1MHz	
Reverse Transfer Capacitance		Cres	_	57	_	pF		
Output Capacitance		Coes	_	31	_		1 – 111112	
SWITCHING CHARACTERISTICS			•	•	•			
Turn-On Delay Time		t _{d(on)}	_	19	_			
Rise Time		t _r	_	27	_	ns	V 45V V 400V	
Turn-Off Delay Time		t _{d(off)}	_	128	_	110	$V_{GE} = 15V, V_{CC} = 400V, \\ I_{C} = 15A, R_{G} = 10\Omega, \\ Inductive Load, \\ T_{j} = +25^{\circ}C$	
Fall Time		t _f	_	32	_			
Turn-On Switching Energy		E _{on}	_	270	_			
Turn-Off Switching Energy		E _{off}	_	86	_	μJ		
Total Switching Energy		E _{ts}	_	356	_			
Turn-On Delay Time		t _{d(on)}	_	17	_			
Rise Time		t _r	_	29	_	ns		
Turn-Off Delay Time		$t_{d(off)}$	1	150	1	115	$\begin{split} V_{GE} &= 15 V, V_{CC} = 400 V, \\ I_{C} &= 15 A, R_{G} = 10 \Omega, \\ Inductive Load, \\ T_{j} &= +175^{\circ}C \end{split}$	
Fall Time		t _f		130				
Turn-On Switching Energy		E _{on}	1	342	I			
Turn-Off Switching Energy		E _{off}		288		μJ		
Total Switching Energy		Ets	_	630	_			
Reverse Recovery Time		t _{rr}	_	150	_	ns	$\frac{\text{ns}}{\frac{\text{A}}{\text{nC}}}$ I _F = 15A, di _F /dt = 200A/µs, $T_j = +25^{\circ}\text{C}$	
Reverse Recovery Current		Irr	_	5.2	_	Α		
Reverse Recovery Charge		Q _{rr}	_	390	_	nC		
Reverse Recovery Time		t _{rr}	_	207		ns A I _F = 15A, di _F /dt = 200A/µs		
Reverse Recovery Current		Irr	_	6.1	_			
Reverse Recovery Charge		Q _{rr}		631		nC		



Typical Performance Characteristics (@TA = +25°C, unless otherwise specified.)

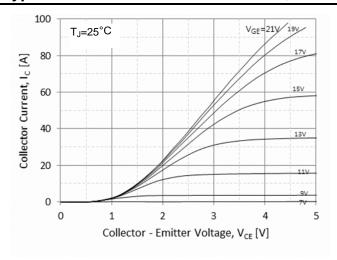


Fig.1 Typical Output Characteristics(T_J=25°C)

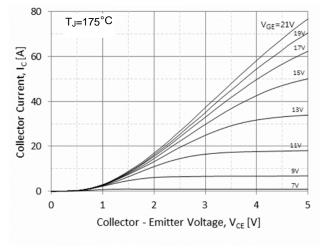


Fig.2 Typical Output Characteristics(T_J=175°C)

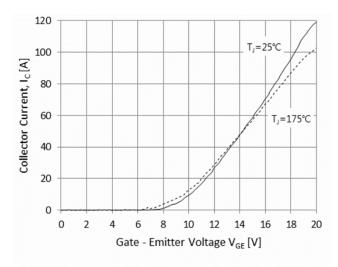


Fig.3 Typical Transfer Characteristics

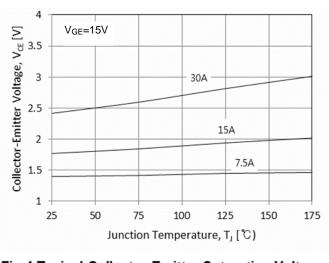


Fig.4 Typical Collector-Emitter Saturation Voltage
-Junction Temperature

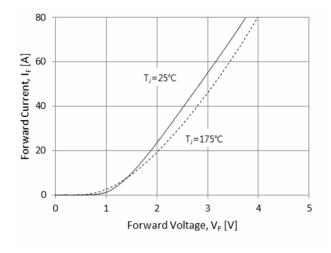


Fig.5 Diode Forward Characteristics

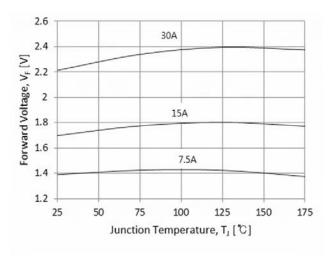
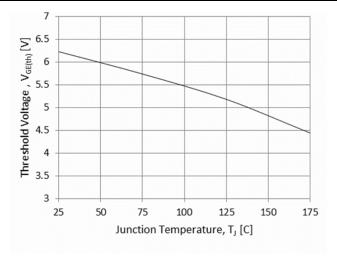


Fig.6 Diode Forward-Junction Temperature



Typical Performance Characteristics (@TA = +25°C, unless otherwise specified.) (continued)



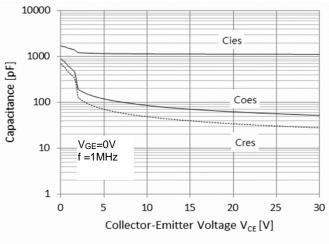


Fig.7 Threshold Voltage-Junction Temperature

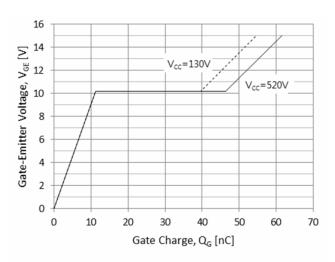


Fig.8 Typical Capacitance

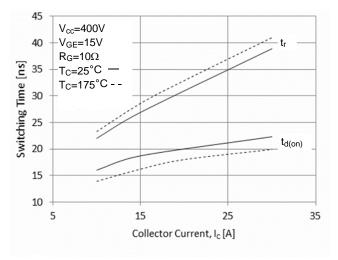


Fig.9 Typical Gate Charge

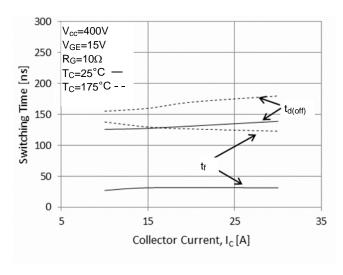


Fig.10 Typical Turn on-Collector Current

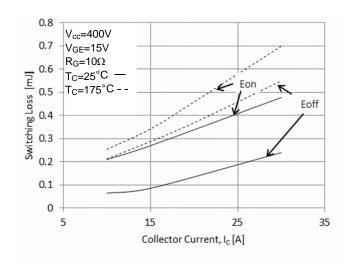
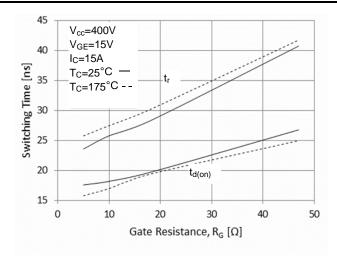


Fig.11 Typical Turn off-Collector Current

Fig.12 Switching Loss-Collector Current



Typical Performance Characteristics (@TA = +25°C, unless otherwise specified.) (cont.)



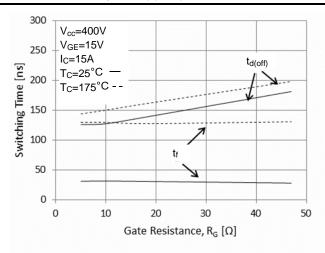


Fig.13 Turn on Characteristics-Gate Resistance

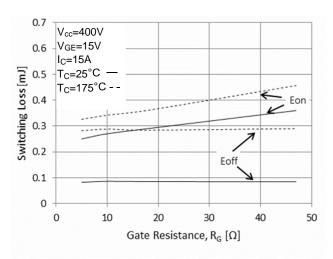


Fig.14 Turn off Characteristics-Gate Resistance

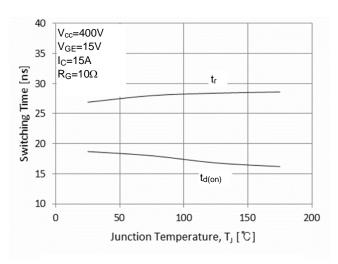


Fig.15 Switching Loss-Gate Resistance

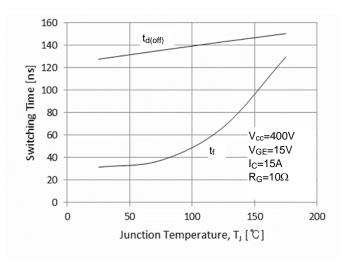


Fig.16 Turn on Characteristics-Junction Temperature

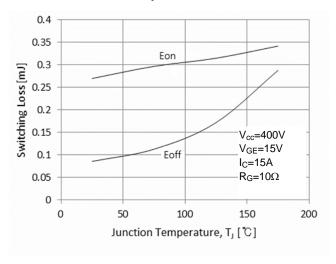


Fig.17 Turn off Characteristics-Junction Temperature

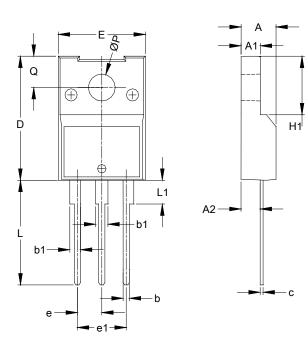
Fig.18 Switching Loss-Junction Temperature



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

ITO220AB (Type MC)



ITO220AB (Type MC)						
Dim	Min	Max	Тур			
Α	4.30	4.80	_			
A 1	2.50	3.10	_			
A2	2.30	2.90	_			
b	0.50	1.00	_			
b1	0.95	1.70	_			
С	0.40	0.80	_			
D	14.50	16.40	_			
H1	6.20	7.20	_			
Е	9.60	10.40	_			
е			2.54			
e1			5.08			
L	12.20	14.20	_			
L1	2.90	4.70	_			
Р	3.00	3.40	_			
Q	2.40	3.50	_			
All Dimensions in mm						

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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